

Docket: APS03-003C  
S/N: 10/742,306



To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

From: Stephen B. Ackerman, Reg. No. 37,761  
Saile Ackerman LLC  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No.: 10/742,306	Filed: 12/19/2003
First Named Inventor: Chng Han Shen	
Title: Various Structure/Height Bumps For Wafer Level-Chip Scale Package	
Group Art Unit: 2811	Examiner: Im, Junghwa M.
Attorney Docket: APS03-003C	

### RESPONSE TO PATENT OFFICE ACTION

Dear Sir:

In response to the office action dated 01/12/2007, please consider the following remarks:

### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on May 14, 2007.

Signature/Date

5/14/07

Stephen B. Ackerman  
Reg. No. 37,761